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RELIABILITY REPORT FOR

DS9490R, Rev A (RoHS)

Dallas Semiconductor

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Prepared by:

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Conclusion:

The following qualification successfully meets the quality and reliability standards required of all Dallas Semiconductor products and processes:

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In addition, Dallas Semiconductor's continuous reliability monitor program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards. The current status of the reliability monitor program can be viewed at http://www.maxim-ic.com/TechSupport /dsreliability.html.*

Module Description

A description of this Module can be found in the product data sheet. You can find the product data sheet at http://dbserv.maxim-ic.com/l_datasheet3.cfm.*

Reliability Derating:

A module device consists of one or more IC's in a single, upward integrated, package. This package is assembled to include batteries, crystals, and other piece parts that make up the configuration of the Module. Because of either the complexity of the package or the included piece parts, standard high temperature reliability testing is not possible. Therefore, in order to determine the reliability of module products, the reliability of each of the piece parts is individually determined, then summed to determine the reliability of the integrated module product. If there are "n" significant components in the module then:

Fr (module) = Fr (1) + Fr (2) + Fr (3) + + Fr (n) Fr (module) = Failure rate of module Fr(n) = Failure rate of the nth component

Failure Rates are reported in FITs (Failures in Time) or MTTF (Mean Time To Failure). The FIT rate is related to MTTF by:

MTTF = 1/Fr

NOTE: MTTF is frequently used interchangeably with MTBF.

,										
Module Device:	Module Units:	Quantity:	Fails:	<u>Ea:</u>	Beta:	MTTF (Yrs):				
CRYSTAL	1	100	0	0.7	0.0	12463				
DS2401	1	2323	0	0.7	0.0	94291				
DS2490	1	80	0	0.7	0.0	9400				
Totals:						5070				

FITs:

9.2

1.2 <u>12.1</u> 22.5

The calculated failure rate for this module/assembly is:

The parameters used to calculate the module failure rate are as follows

Cf: 60% Tu: 55 °C Vu: 5.5 Volts

The reliability data follows. At the start of this data is the module assembly information. This is a description of the module. The next section is the detailed reliability data for each stress found in the qualification / monitor. If there are additional processes or assemblies used as part of this report, a description of each will follow which includes the respective reliability data for that process/ assembly. The reliability data section includes the latest data available. Some of this data may be generic with other packages or products.

* Some proprietary products may be excepted from this requirement

Assembly Information	tion:						
Assembly Site:		Fastech					
Pin Count:		0					
Package Type:		Dongle or Fob (RoHS)					
Body Size:		0					
Mold Compound:							
Lead Frame: Lead Finsh:		PCB; FR4 Sn Dip 100%					
Die Attach:		?					
Bond Wire / Size		: /					
Flammability:		, UL 94-V0					
Moisture Sensitiv	ity						
(JEDEC J-STD							
Date Code Rang	e:	0600 to 0619					
MECHANICAL LIFE							<u> </u>
DESCRIPTION	DATE CD	CONDITION	REA	DPOINT	QTY	FAILS	FA#
INSERTIONS/EXTRACT	S 0600	25 C	500	CYS	5	0	
				Total:		0	
STORAGE LIFE							
DESCRIPTION	DATE CD	CONDITION	REA	DPOINT	QTY	FAILS	FA#
STORAGE LIFE	0619	85 C	1000	HRS	77	0	
STORAGE LIFE	0619	85 C	1000	HRS	77	0	
STORAGE LIFE	0619	85 C	1000	HRS	77	0	
				Total:		0	
TEMPERATURE CYC	LE						
DESCRIPTION	DATE CD	CONDITION	REA	DPOINT	QTY	FAILS	FA#
TEMP CYCLE	0619	-40 TO 85C		CYS	77	0	
TEMP CYCLE	0619	-40 TO 85C		CYS	77	0	
TEMP CYCLE	0619	-40 TO 85C	1000	CYS	77	0	
				Total:		0	<u> </u>
UNBIASED MOISTUR	RE RESIST	ANCE					
DESCRIPTION	DATE CD	CONDITION	REA	DPOINT	QTY	FAILS	FA#
MOISTURE SOAK	0619	60C/90% R.H.	1000	HRS	77	0	
MOISTURE SOAK	0619	60C/90% R.H.		HRS	77	0	
MOISTURE SOAK	0619	60C/90% R.H.	1000	HRS	77	0	
				Total:		0	